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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/618,874	07/14/2003	Mukul Saran	TI-30597.1	5871
23494	7590 12/28/2004		EXAM	INER
TEXAS IN	STRUMENTS INCORPO	HA, NAT	HA, NATHAN W	
P O BOX 65 DALLAS, T	5474, M/S 3999 X 75265		ART UNIT	PAPER NUMBER
,			2814	
			DATE MAILED: 12/28/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
	10/618,874	SARAN, MUKUL				
Office Action Summary	Examiner	Art Unit				
	Nathan W. Ha	2814				
The MAILING DATE of this communicati Period for Reply	on appears on the cover sheet with	h the correspondence address				
A SHORTENED STATUTORY PERIOD FOR THE MAILING DATE OF THIS COMMUNICATORY Extensions of time may be available under the provisions of 37 after SIX (6) MONTHS from the mailing date of this communication of the period for reply specified above is less than thirty (30) dayout If NO period for reply is specified above, the maximum statutor Failure to reply within the set or extended period for reply will, the Any reply received by the Office later than three months after the earned patent term adjustment. See 37 CFR 1.704(b).	FION. CFR 1.136(a). In no event, however, may a relation. In a reply within the statutory minimum of thirty and will expire SIX (6) MONT by statute, cause the application to become ABA	ply be timely filed (30) days will be considered timely. THS from the mailing date of this communication. ANDONED (35 U.S.C. § 133).				
Status	•					
1) Responsive to communication(s) filed or	n <u>08 October 2004</u> .					
2a) This action is FINAL . 2b) This action is non-final.						
. —	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
4) ⊠ Claim(s) <u>9-14</u> is/are pending in the appli 4a) Of the above claim(s) is/are w 5) ☐ Claim(s) is/are allowed. 6) ⊠ Claim(s) <u>9-14</u> is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction	ithdrawn from consideration.	••				
Application Papers						
9)☐ The specification is objected to by the Ex	caminer.					
10) The drawing(s) filed on is/are: a)	0) ☐ The drawing(s) filed on is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.					
Applicant may not request that any objection						
Replacement drawing sheet(s) including the 11) The oath or declaration is objected to by	•	• •				
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for fa a) All b) Some * c) None of: 1. Certified copies of the priority doc 2. Certified copies of the priority doc 3. Copies of the certified copies of the application from the International * See the attached detailed Office action for	uments have been received. uments have been received in Ap ne priority documents have been i Bureau (PCT Rule 17.2(a)).	oplication No received in this National Stage				
AMarkara M. A.	•					
Attachment(s) 1) Notice of References Cited (PTO-892)	4) Interview Si	ummary (PTO-413)				
2) Notice of Draftsperson's Patent Drawing Review (PTO-9	Paper No(s)	/Mail Date				
 Information Disclosure Statement(s) (PTO-1449 or PTO Paper No(s)/Mail Date 	formal Patent Application (PTO-152) 					

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

2. Claims 9-1 are rejected under 35 U.S.C. 102(e) as being anticipated by Ning et al. (US 6,677,635, previously cited, hereinafter, Ning.)

In regard to claim 9, in fig. 5, Ning discloses a method of forming an IC capacitor (see the abstract), comprising:

providing a silicon substrate, not shown, with a first dielectric film 11 (col. 4, line 9) containing at least one copper layer 10 (col. 4, lines 8-10);

forming a second dielectric layer 12, or etch-stop/barrier layer, (col. 4, lines 13-14) over the first dielectric layer and the copper layer wherein the second dielectric layer (etch-stop layer) contacts the copper layer;

forming a first conductive layer 16, or cap plate, (col. 4, line 43) over the first dielectric layer wherein the first conductive layer contacts the second electric layer (etch-stop layer), see fig.5; and

removing portion of the first conductive layer such that a portion of the second dielectric layer remains between the first conductive layer and the copper layer wherein these layers formed a capacitor structure. See col. 4, lines 1-10.

In regard to claim 10, Ning further discloses forming copper contacts to the first conductive layer, see fig.5 (from the top); and

forming a second copper layer that electrically contacts the copper contacts (fig. 5, where in the contacts made through a via in the dielectric layer.)

In regard to claim 11, the first conductive layer suggested to be aluminum, see col. 4, lines 45-47.

In regard to claim 12, see fig. 5, where the dielectric layer is formed using a least two dielectric films, including 15, for example.

In regard to claim 13, layer 12 may be considered as a barrier layer.

In regard to claim 14, the dielectric layer is made of silicon nitride. See col. 4, lines 15-17.

It should be noted that even though Ning does not label dielectric layer 12 as a etch-stop/barrier layer, but this layer is made of the same material as disclosed by the instant invention, Silicon nitride (col. 4, lines 17-19). Therefore, the dielectric layer 12 functions as a barrier layer.

Response to Arguments

3. Applicant's arguments filed 8/23/04 have been fully considered but they are not persuasive. For instance, Applicants contend that the cited art does not disclose an

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invention.

etch-stop/barrier layer. As discussed above, the dielectric layer 12 is made of the same material, silicon nitride. This material is in fact the same material as the etch-stop layer as claimed. Therefore, the Ning's device indeed discloses an etch-stop layer, which is capable of having the same property as the etch-stop layer as claimed in the instant

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Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nathan W. Ha whose telephone number is (571) 272-1707. The examiner can normally be reached on M-TH 8:00-7:00(EST).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

Nathan Ha

December 22, 2004

Intra with